NXP

Final Product Change Notification	201506034F01

Issue Date: 13-Jul-2015
Effective Date: 27-Oct-2015

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QUALITY

Management Summary
Introduction DAF (Die Attach Film) in TSOP6 at APM.

Change Category

[ ] Wafer Fab process	[ ] Assembly Process	[ ] Product Marking	[ ] Design
[ ] Wafer Fab materials	[X] Assembly Materials	[ ] Electrical spec./Test coverage	[ ] Mechanical Specification
[ ] Wafer Fab location	[ ] Assembly Location	[ ] Test Location	[ ] Packing/Shipping/Labeling

Introduction DAF in TSOP6 at APM

Details of this Change

For TSOP6-subpackage from assembly plant Malaysia (APM) is available with Wafer Back Coat (WBC).
For WBC will be replaced by Die Attach Film (DAF).

Why do we Implement this Change
Standardization of the backend part of the assembly manufacturing process.

Identification of Affected Products
Product identification does not change

Product Availability

Sample Information
Samples are available upon request

Production
Planned first shipment 21-Oct-2015

Impact

no impact to the product's functionality anticipated.

Data Sheet Revision
No impact to existing datasheet

Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 12-Aug-2015.

Remarks

n.a.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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